	CONNECTING S INDUSTRIES* international and Pan	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	tion of the	ne substances asses all lowe	within the er level mate	manufacture erials for wh	er listed it hich the m	em. Note: anufacture	if the item is an as er has engineering	ssembly with lowe responsibility.	
1752-21.1					Form Type Distribute	<ul> <li>Declaration Class *</li> <li>Class 6 - RoHS Yes/No, Homogeneous Mater</li> </ul>					ous Materia	als and Mfg Information				
Supplier	· Information															
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*					
onsemi											2024-05-21					
Contact N	ame	Title - Contact			]	Phone - Contact*					Email - Contact*					
Product-E	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized	d Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*						
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
			Number Mfr Item Name				Effective Date	e Date Version Manufacturing Site		ing Site	v	Veight*	UOM	Unit Type		
			BR TS6P GPPN 20A 600V			2024-05-21 TSO		TSCBE		7	671.0	mg	Each			
/Ianufa	cturing Proccess Informat	tion					-									
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 N		J-STD-020 MS	L Rating	Peak Process Body		ody Temperature Max Time at Peak		Temperature Number of		nber of Reflow Cyc	cles		
	Matte Tin (Sn) - annealed		U Alloy NA			0 C		С	30		second	is 3				
omments																
or more i	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die Attach Solder	200.0	mg	Supplier	Silver (Ag)	7440-22-4		5	mg
			А	Lead (Pb)	7439-92-1	7a	185	mg
			Supplier	Tin (Sn)	7440-31-5		10	mg
umper	60.4	mg	Supplier	Iron (Fe)	7439-89-6		0.05	mg
			Supplier	Copper (Cu)	7440-50-8		60.34	mg
			Supplier	Phosphorus (P)	7723-14-0		0.01	mg
Lead Frame	2315.0	mg	Supplier	Iron (Fe)	7439-89-6		1.852	mg
			Supplier	Copper (Cu)	7440-50-8		2312.6851	mg
			Supplier	Phosphorus (P)	7723-14-0		0.463	mg
Mold Compound-Black	4807.0	mg	В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		96.14	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		721.05	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		96.14	mg
			Supplier	Carbon Black (C)	1333-86-4		48.07	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		480.7	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3364.8999	mg
Plating	248.6	mg	Supplier	Tin (Sn)	7440-31-5		248.6	mg
Silicon Dice	40.0	mg	Supplier	Silicon (Si)	7440-21-3		39.992	mg
			В	Nickel (Ni)	7440-02-0		0.004	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg